

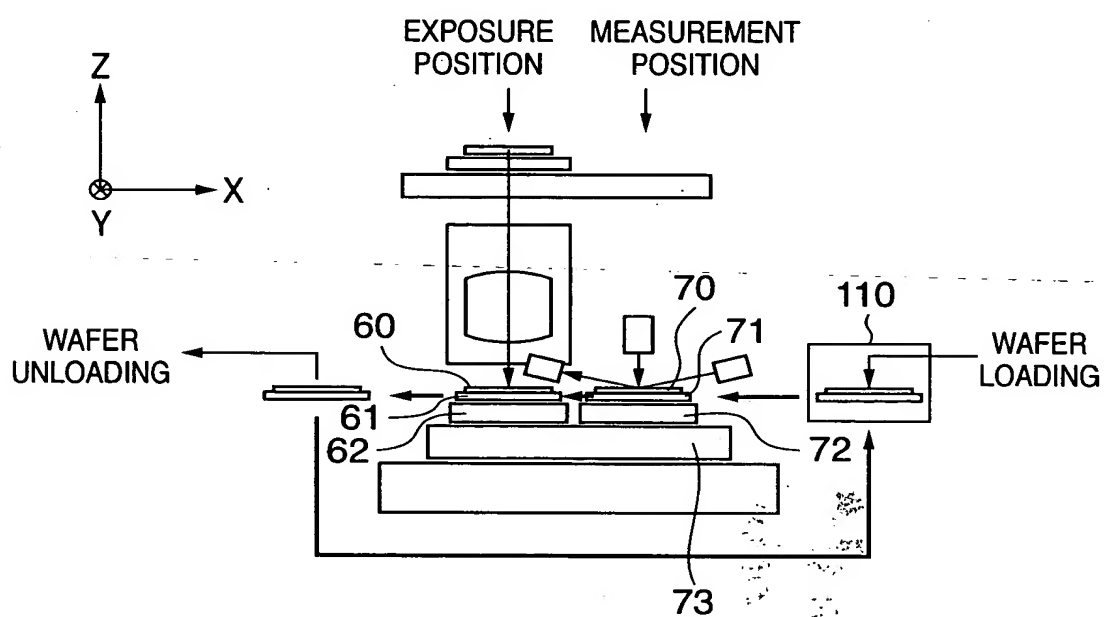
FIG. 1

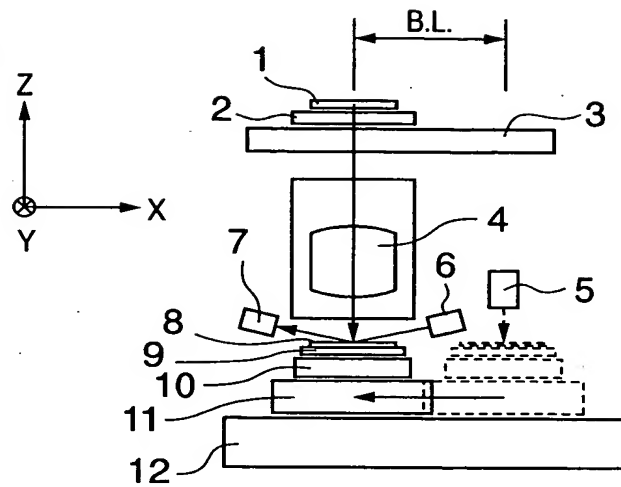
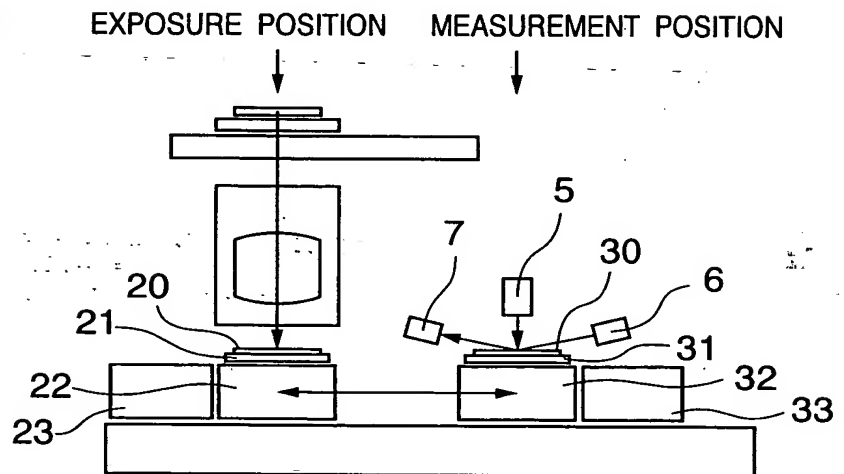
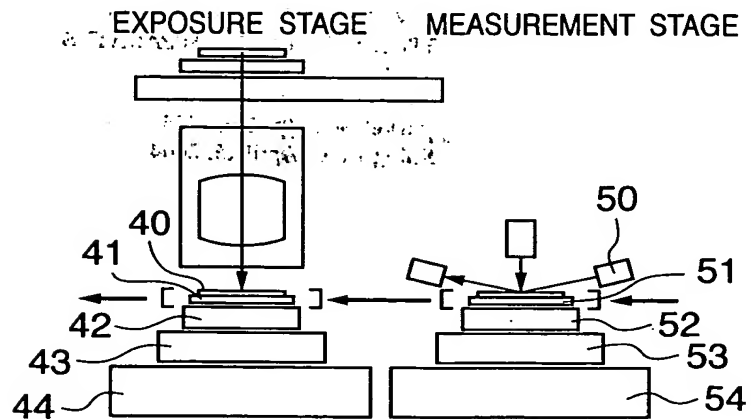
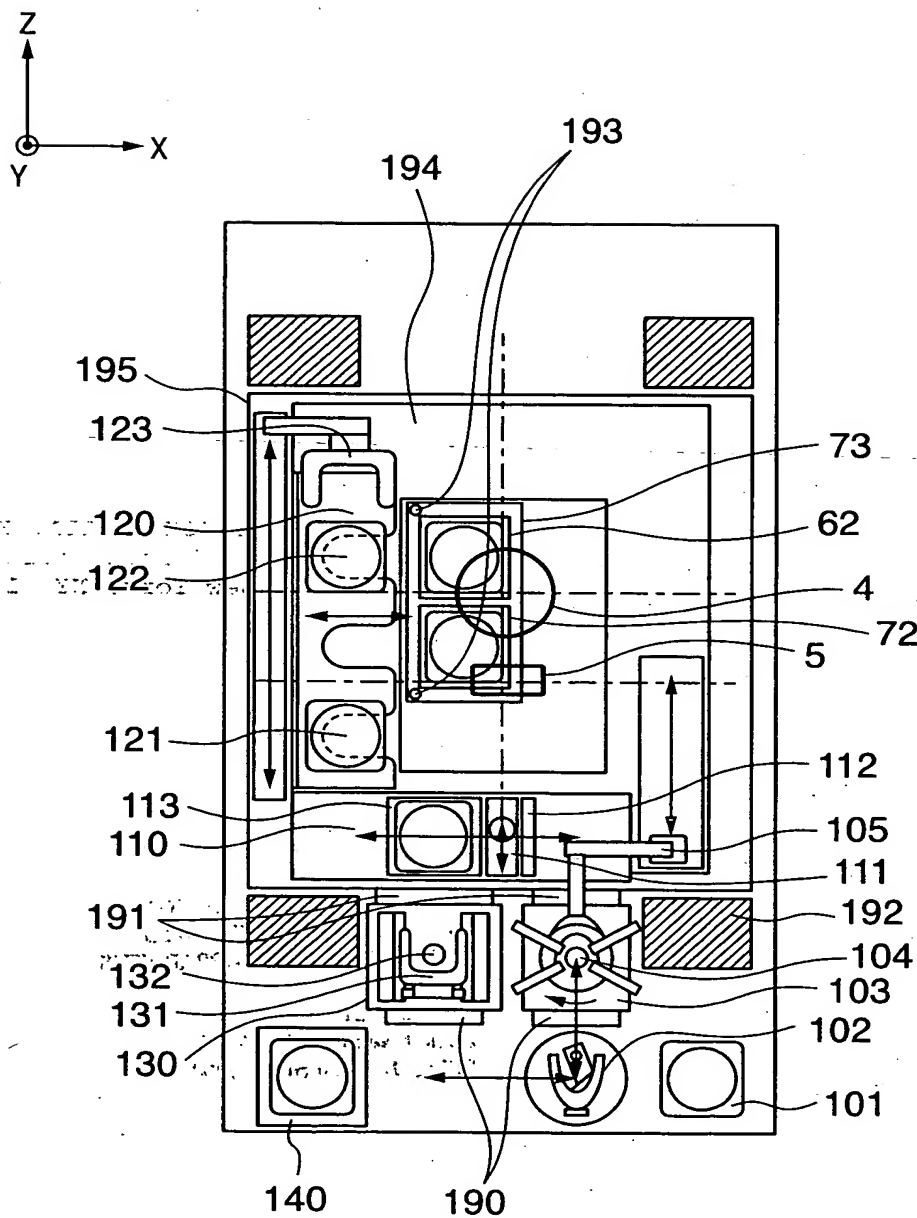
FIG. 2A**FIG. 2B****FIG. 2C**

FIG. 3



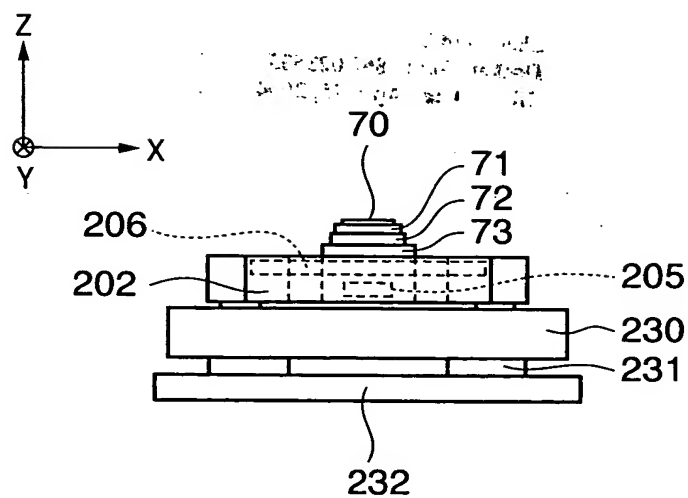


FIG. 5A

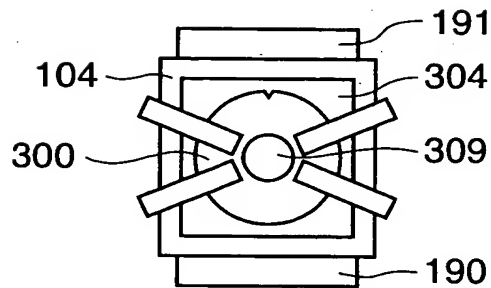


FIG. 5B

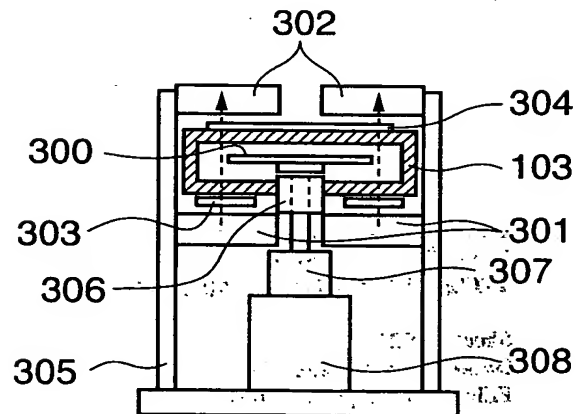


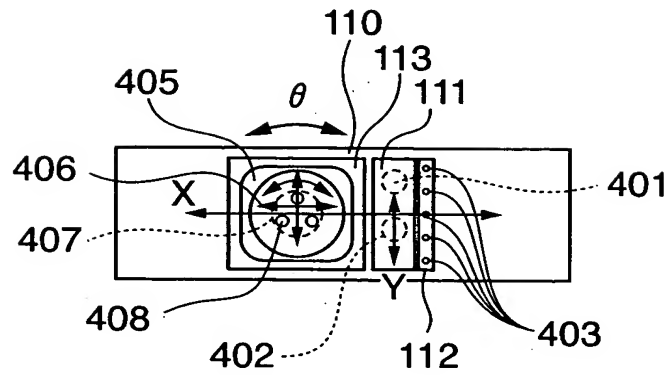
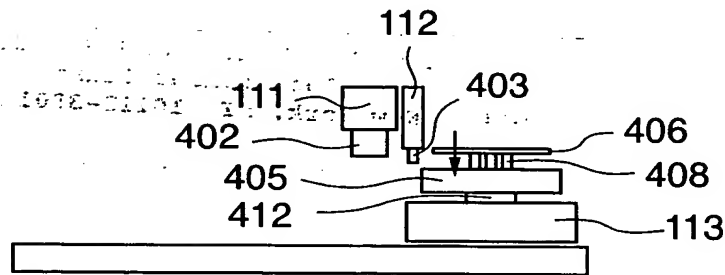
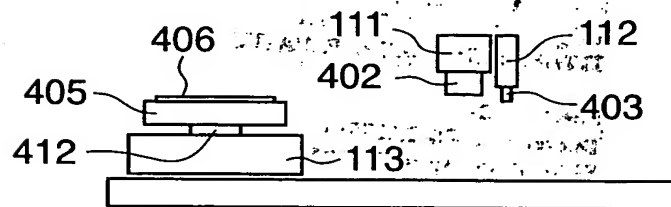
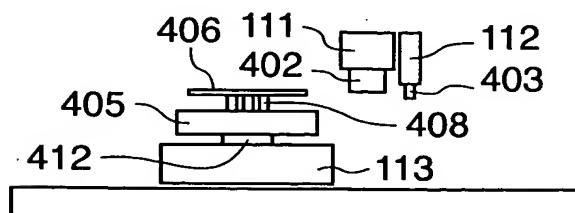
FIG. 6A**FIG. 6B****FIG. 6C****FIG. 6D**

FIG. 7A

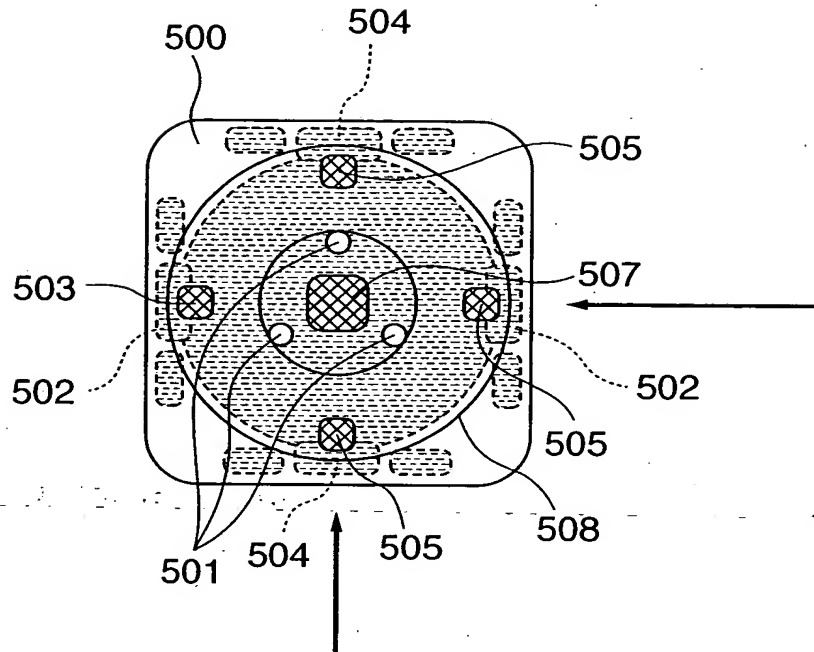


FIG. 7B

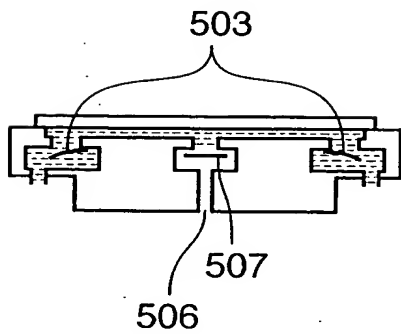
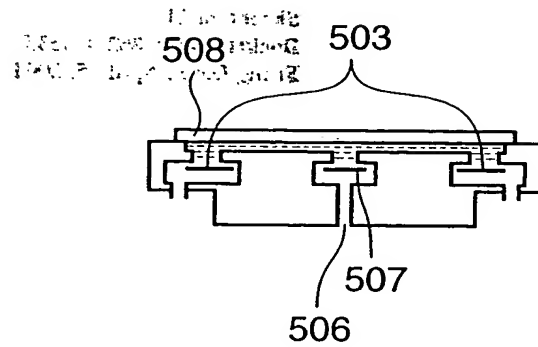


FIG. 7C



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FIG. 8A

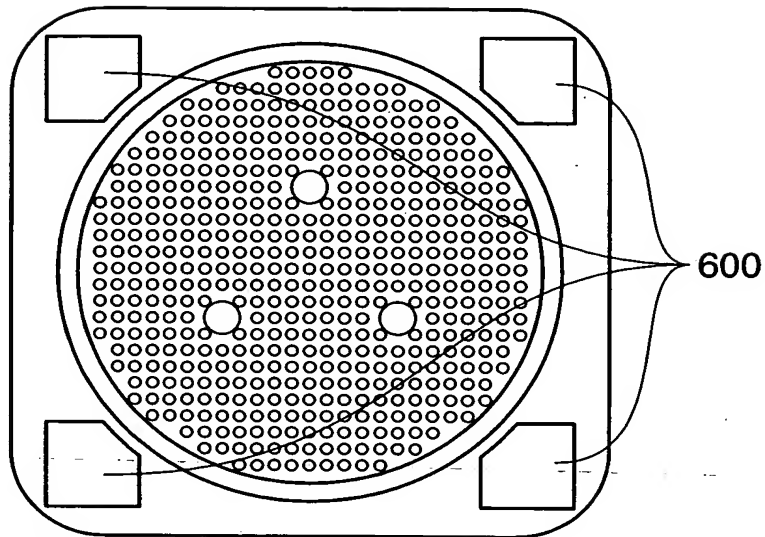
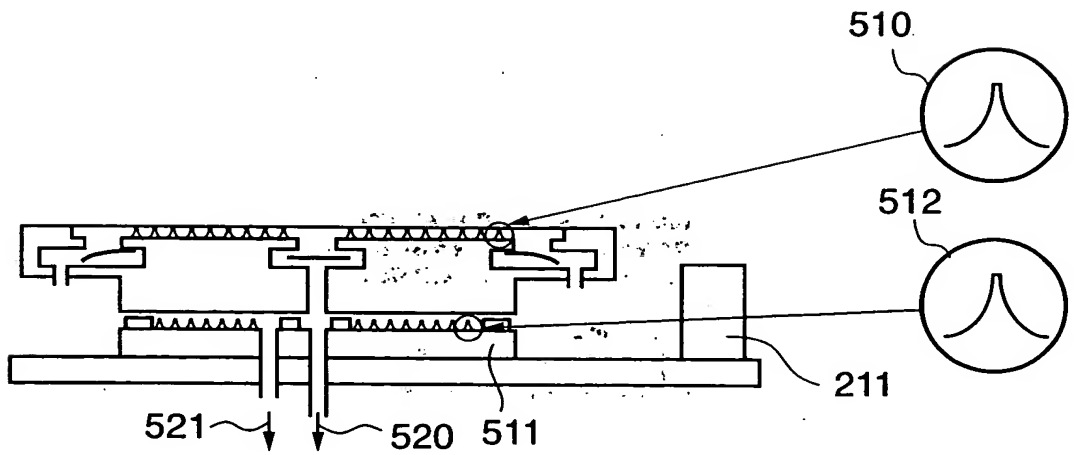


FIG. 8B is a cross-sectional view of the component 600 of FIG. 8A, taken along line A-A. The component 600 is shown as a thin, circular disk with a grid of small holes. The disk is mounted on a substrate 211, which is shown in cross-section. The mounting is achieved by four trapezoidal tabs 510, which are secured by screws 512. The screws 512 are shown in cross-section, passing through the tabs 510 and the component 600 into the substrate 211. The substrate 211 has a central opening 521 and a central protrusion 520. The component 600 is positioned such that its central opening 521 aligns with the central protrusion 520 of the substrate 211. The component 600 is also labeled with 511.

FIG. 8B



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FIG. 9A

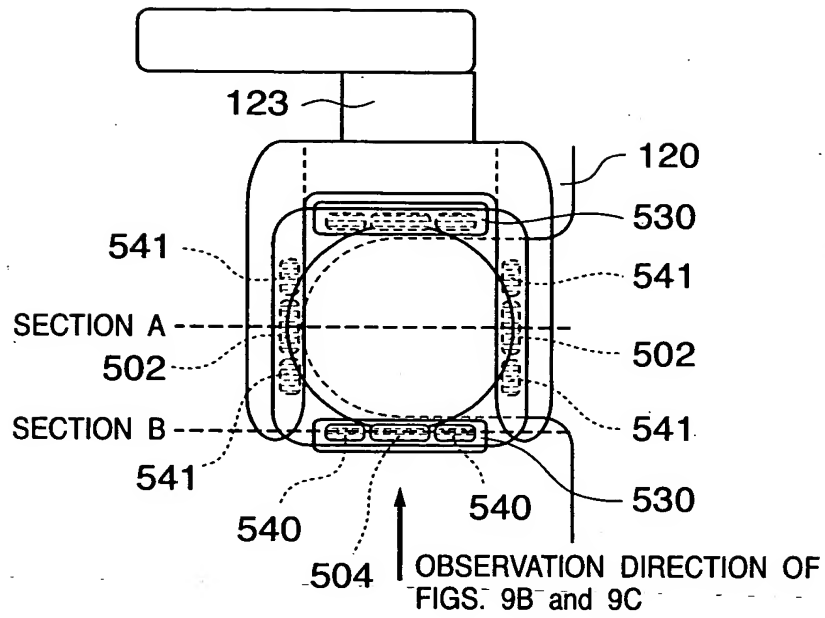


FIG. 9B

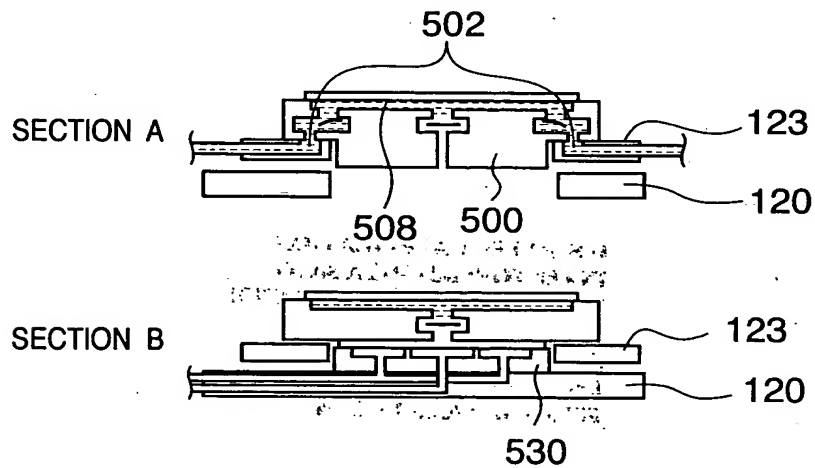
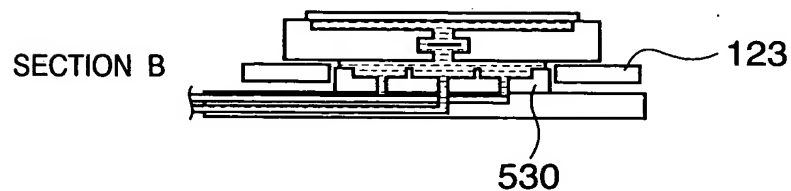


FIG. 9C



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FIG. 10A

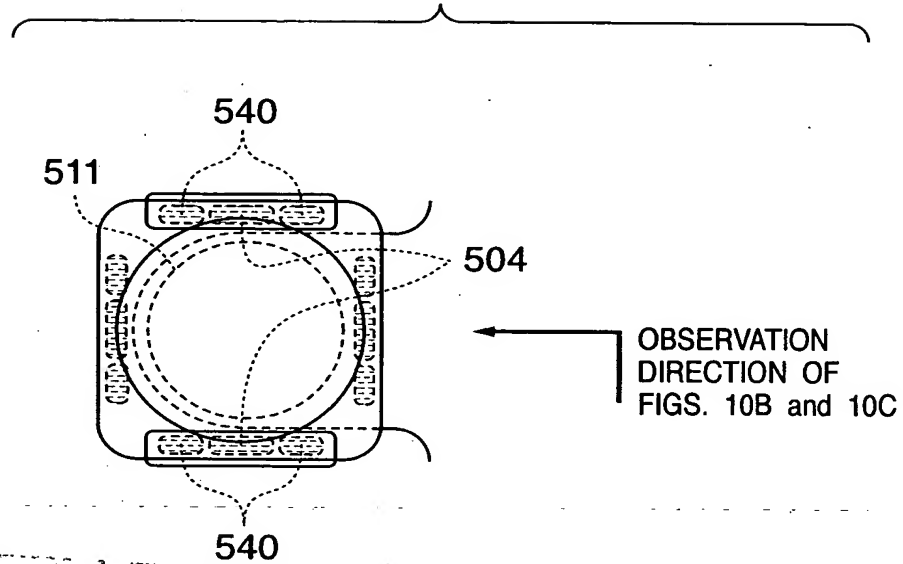


FIG. 10B

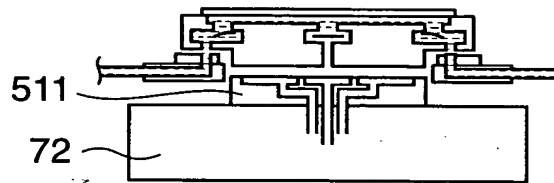


FIG. 10C

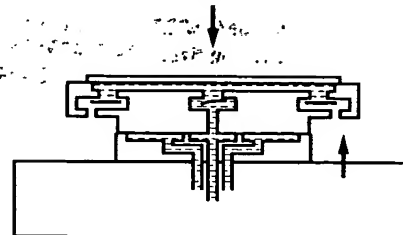
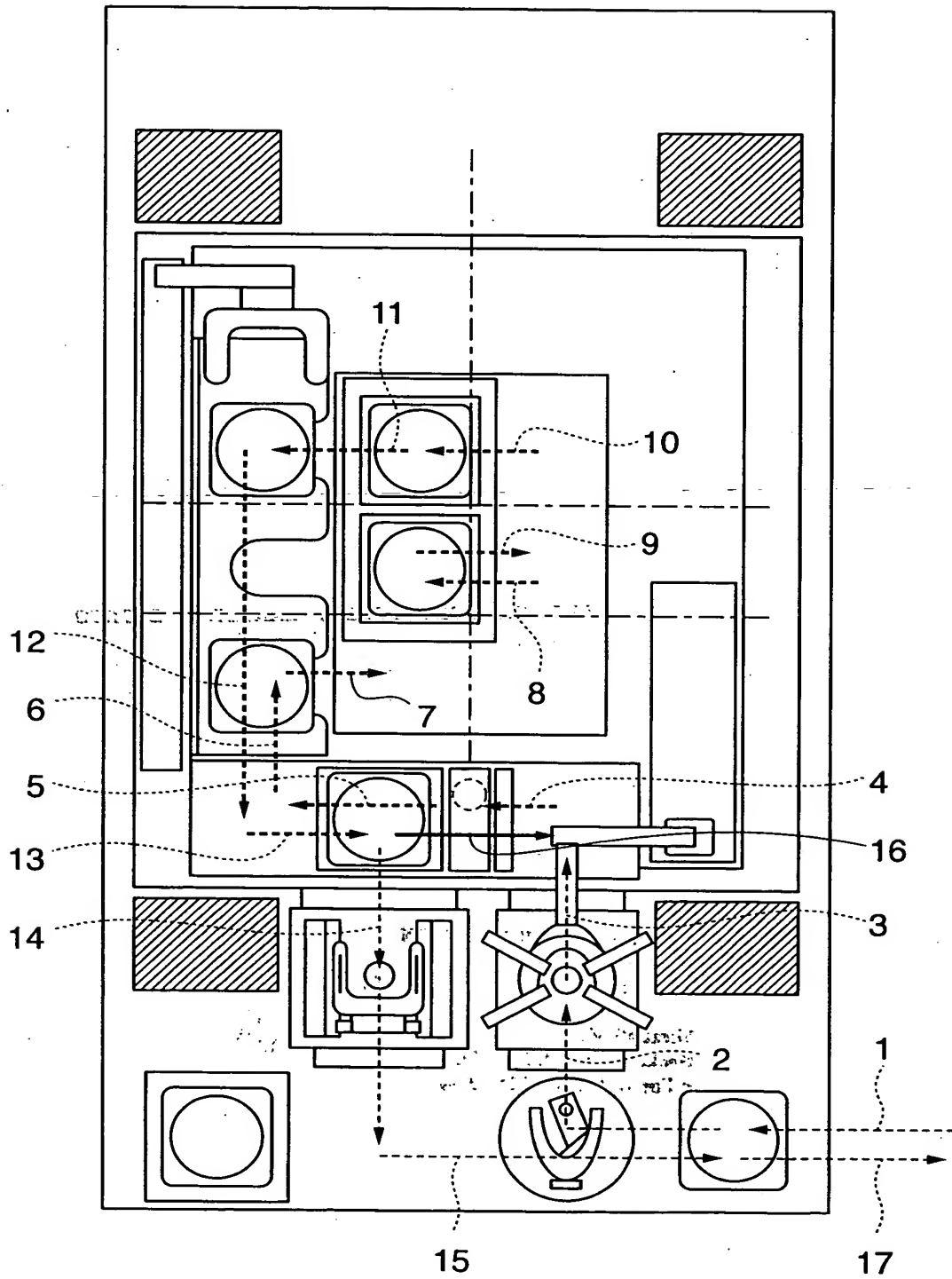


FIG. 11

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FIG. 12

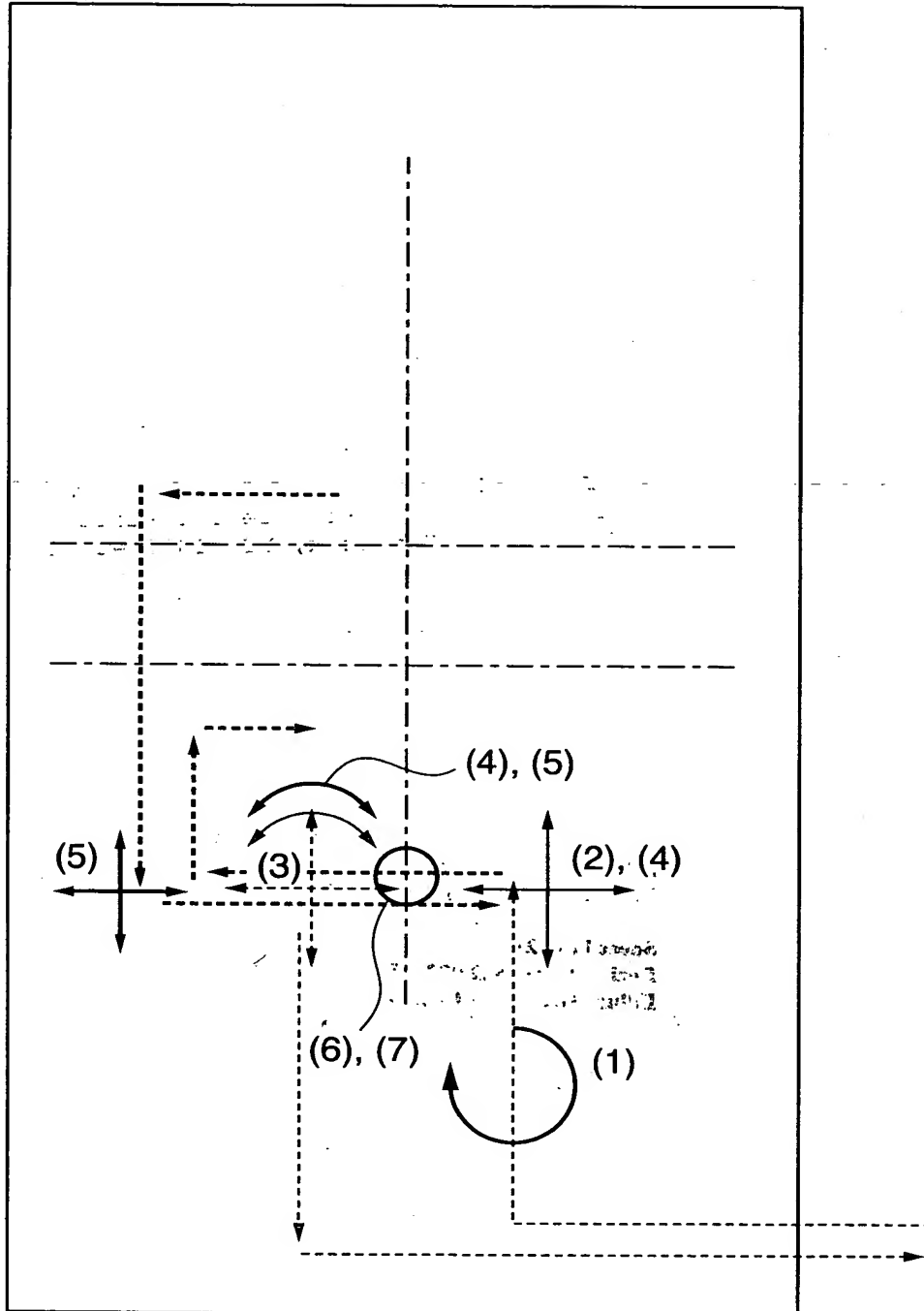


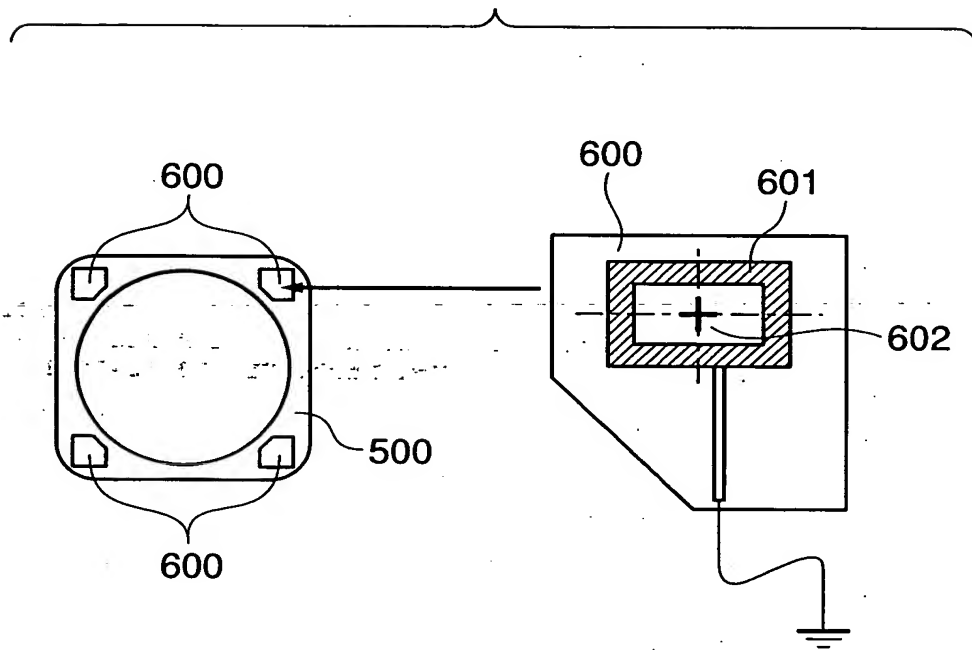
FIG. 13

FIG. 14

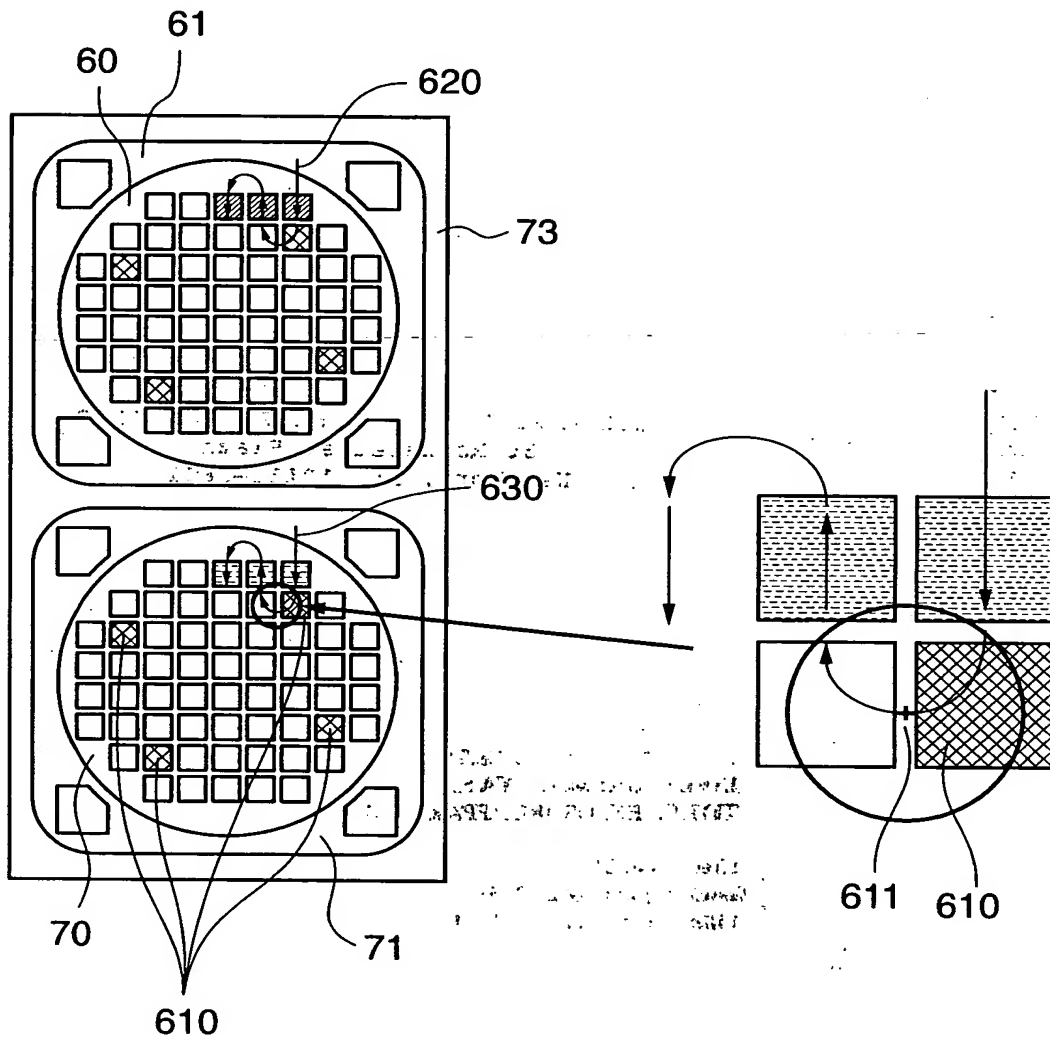


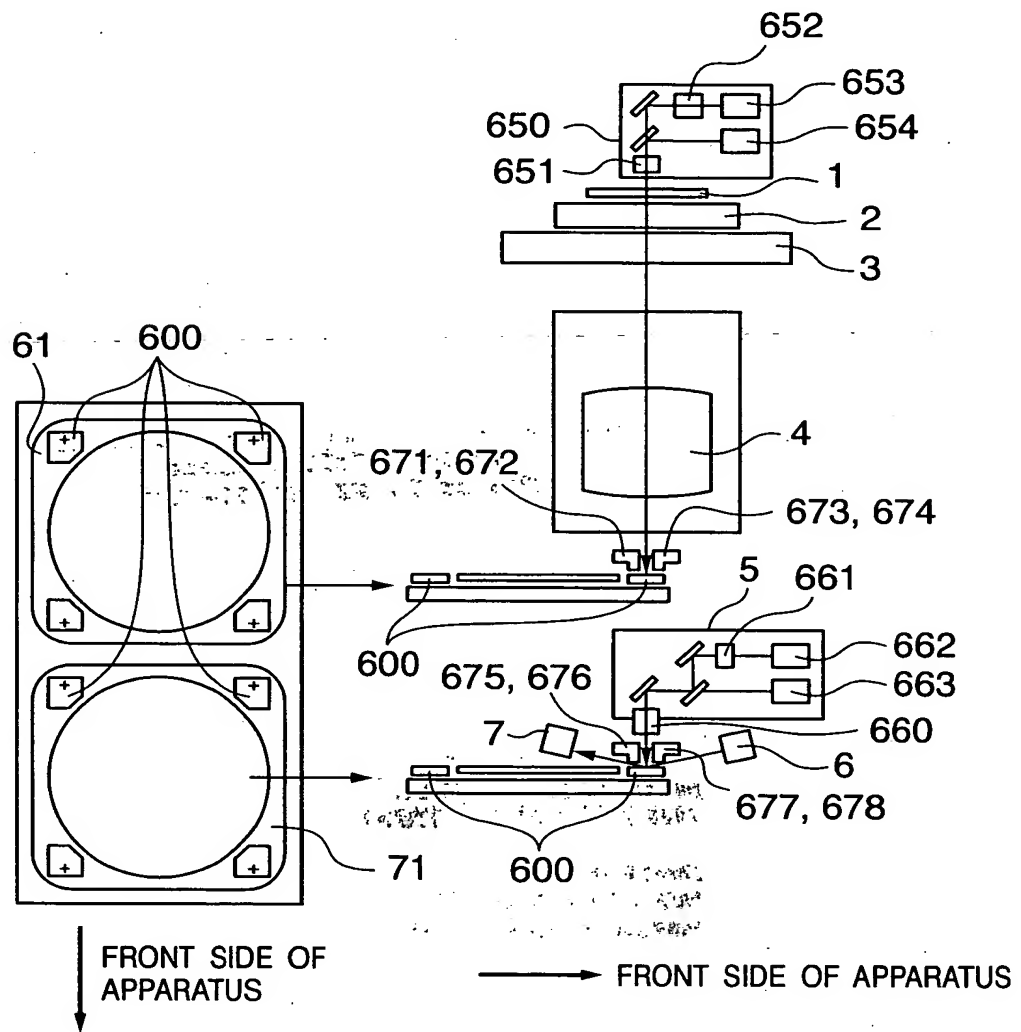
FIG. 15

FIG. 16A

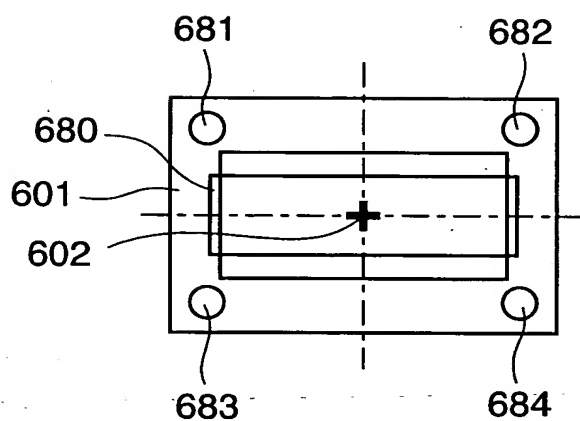


FIG. 16B

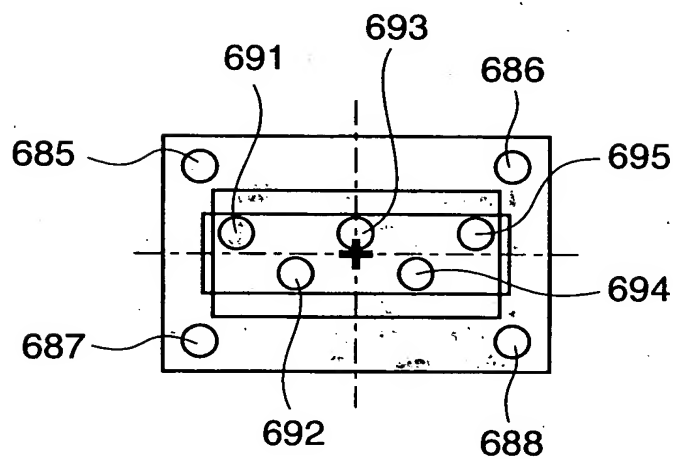


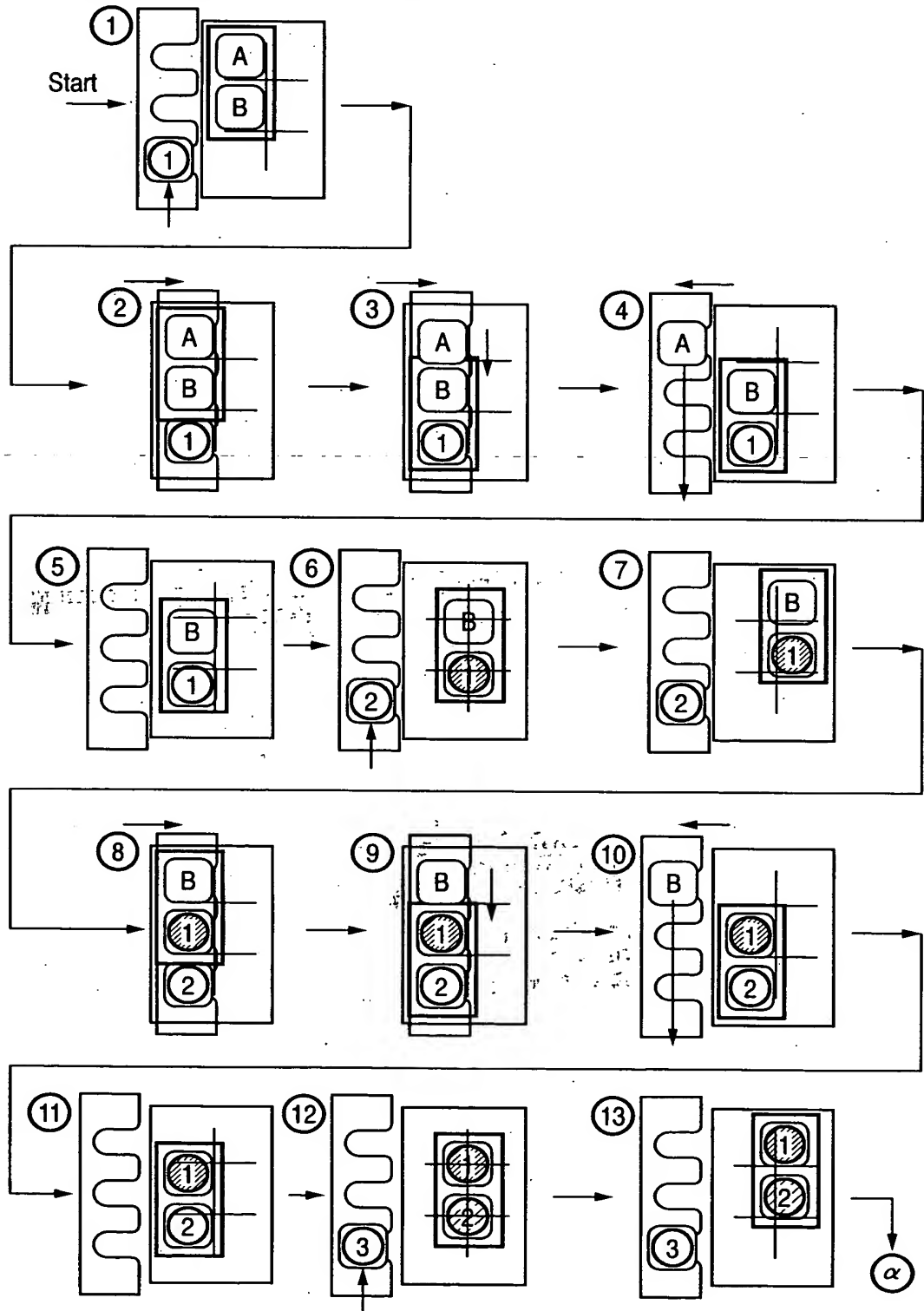
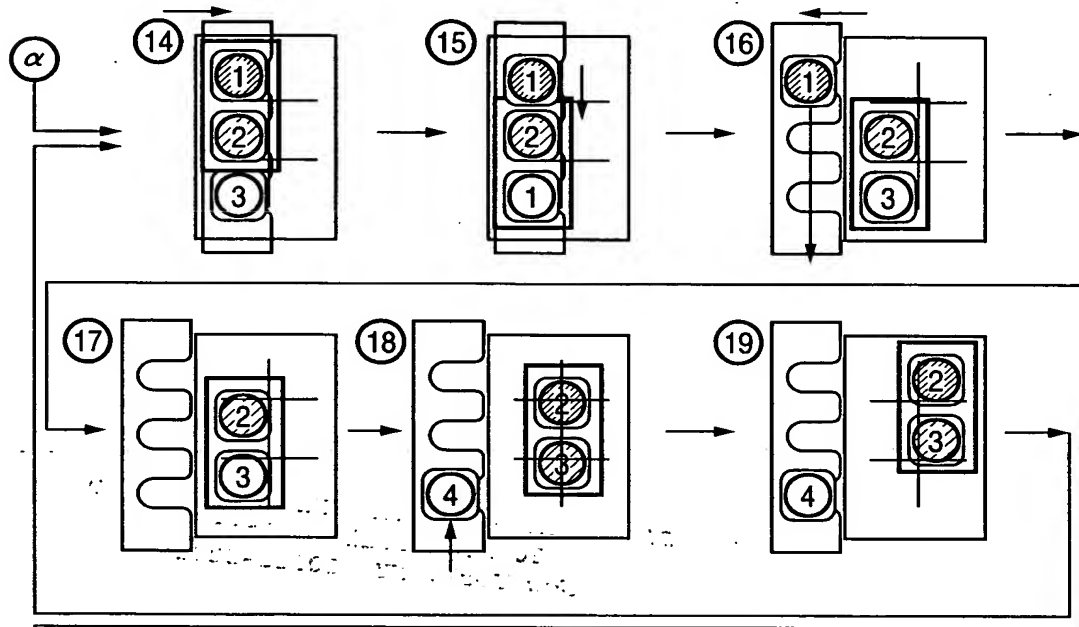
FIG. 17**1. MEASUREMENT OF FIRST WAFER**

FIG. 18

3. (MEASUREMENT OF THIRD TO (N-1)TH WAFERS) &
(EXPOSURE OF SECOND TO (N-2)TH WAFERS)



4. (MEASUREMENT OF NTH WAFER) & (EXPOSURE OF (N-1)TH WAFER)

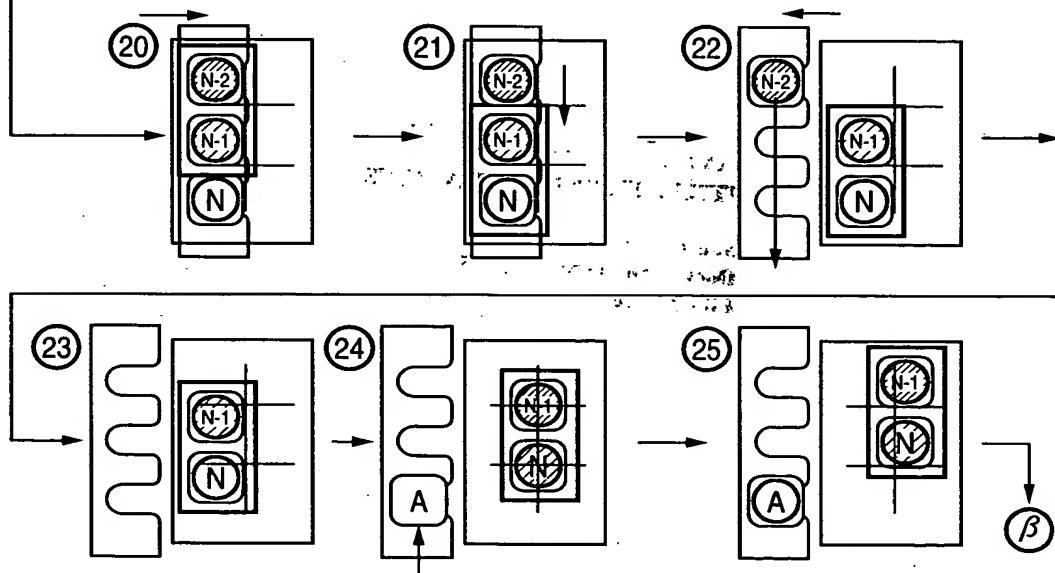


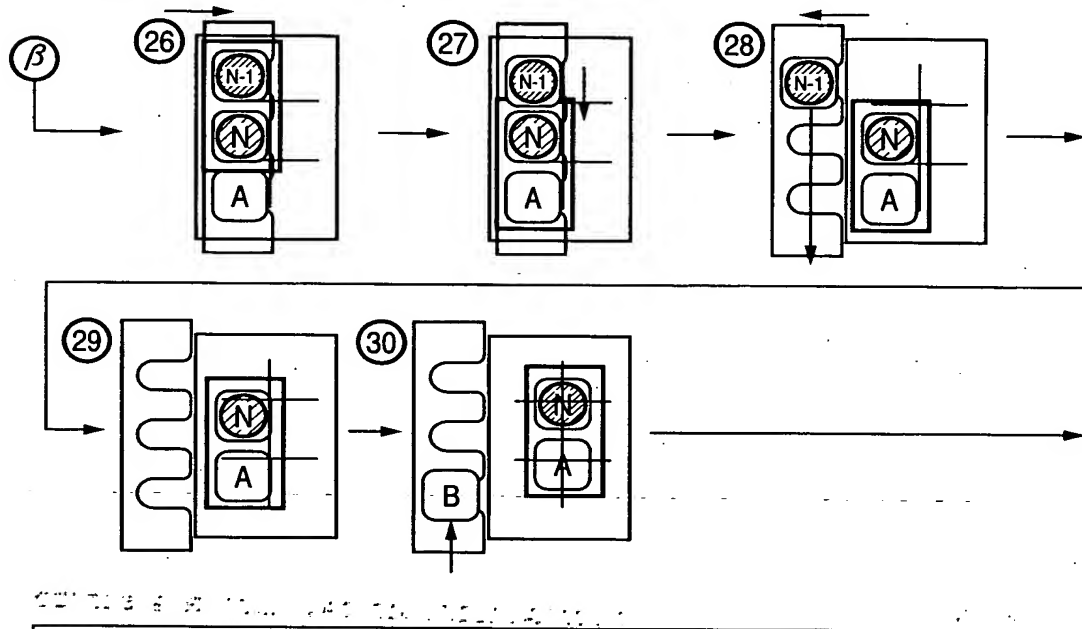
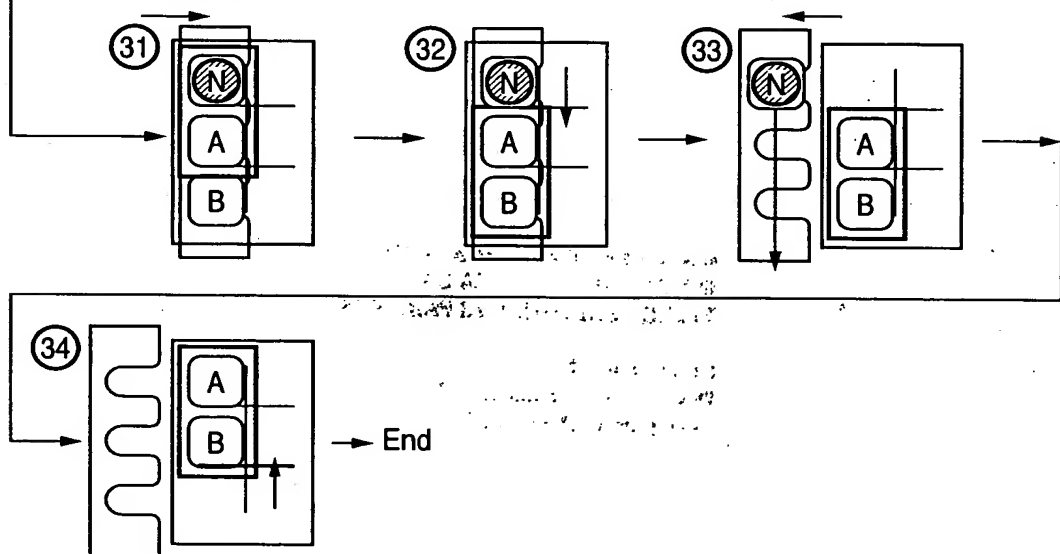
FIG. 19**5. MEASUREMENT OF NTH WAFER****6. END PROCESS**

FIG. 20

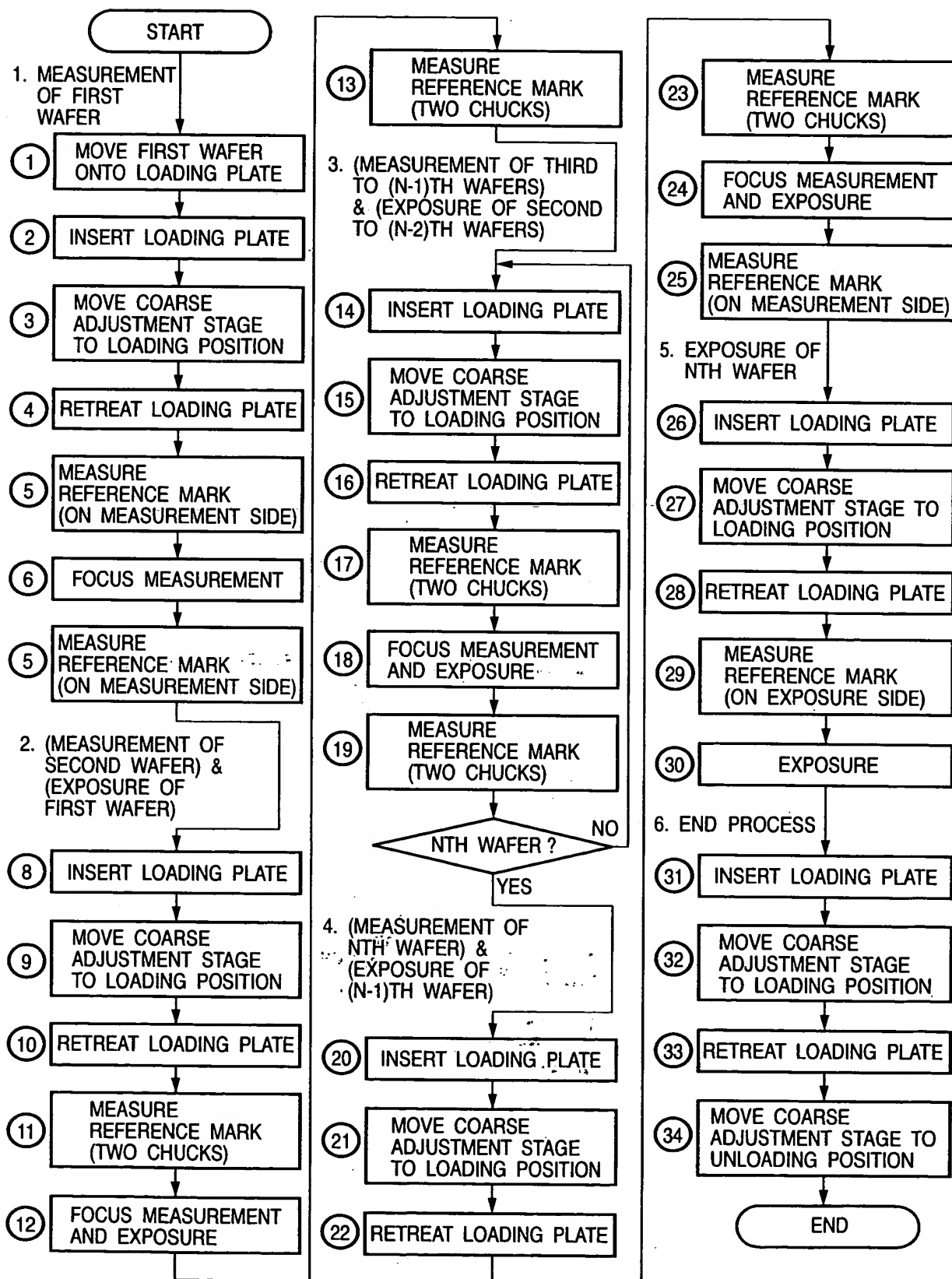


FIG. 21